
PCI Express Card Edge Connector, Vertical, DIP Type

1. SCOPE**1.1. Contents**

This specification covers the performance, tests and quality requirements for the TE PCI Express Card Edge connector, Vertical, DIP Type.

1.2. Qualification

When tests are performed on the subject product line, procedures specified in Figure 1 shall be used. All inspections shall be performed using the applicable inspection plan and product drawing.

2. APPLICABLE DOCUMENT

The following documents form a part of this specification to the extent specified herein. Unless otherwise specified, the latest edition of the document applies. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

2.1. Tyco Electronics Documents

- 109-1: General Requirements for Test Specifications
- 109-197 : Test Specification (TE test Specifications vs EIA and IEC Test Methods)
- TEC-109-201: Component Heat Resistance to Lead-Free Reflow Soldering.
- 109-202: Component Heat Resistance to Wave Soldering.
- 501-57838: Qualification Test Report.

2.2. Commercial Standard

- EIA-364: Electrical Connector/Socket Test Procedures Including Environmental Classifications.
- JESD22-B102D: Solderability Test Method.

3. REQUIREMENTS**3.1. Design and Construction**

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing.

3.2. Materials

Materials used in the construction of this product shall be as specified on the applicable product drawing.

3.3. Ratings

- A. Voltage: 50 volts AC/DC.
- B. Current: 1.1 amperes.
- C. Temperature: -40 to 85°C.

3.4. Performance Requirement and Test Description

Product is designed to meet the electrical, mechanical and environmental performance requirements specified in Figure1. Unless otherwise specified, all tests shall be performed at ambient environmental conditions per EIA-364.

3.5. Test Requirements and Procedures Summary

Test Description	Requirement	Procedure
Examination of product.	Meets requirements of product drawing.	EIA-364-18 Visual and dimensional inspection per product drawing.
ELECTRICAL		
Low level contact resistance.	30 mΩ maximum.	EIA-364-23, Refer to Figure 3 Measure by dry circuit, 20 mV max open circuit at 100 mA max.
Dielectric withstanding voltage.	1 minute hold with no breakdown or flashover.	EIA 364-20C Method B Test between adjacent contacts of unmated connector assemblies. Voltage: 500 VAC, Current leakage: 0.5 mA max.
Insulation resistance.	1000 MΩ minimum.	EIA-364-21 After 500 V DC for 1 minute, measure the insulation resistance between the adjacent contacts of unmated connector assemblies.
MECHANICAL		
Mating force.	117g per contact pair maximum.	EIA-364-13 Measure force necessary to mate the connector assemblies at a max of 12.5 mm/minute.
Unmating force.	15g per contact pair minimum.	EIA-364-13 Measure force necessary to unmate the connector assemblies at a max of 12.5 mm/minute.
Durability.	See NOTE	EIA-364-09 Mate and unmated connector assemblies for 50 cycles at a maximum rate of 200 cycles/hour.
Reseating.	See NOTE	Manually unplug/plug the connector. Perform 3 such cycles.
Vibration, random.	No discontinuities of 1 μs or longer duration. See NOTE	EIA-364-28, Test condition VII, Test letter D Subject mated connectors to 3.1 g's RMS. 15 minutes in each of three mutually perpendicular planes.
ENVIRONMENTAL		
Solderability.	The inspected area of each lead must have 95% solder coverage minimum.	JESD22-B102D, Condition C Steam Aging Preconditioning: 93 +3/-5°C, 8 hours ±15 min. Solder Temperature: 245 ±5°C. Solder Immersion Time: 5 ±0.5 s.

Figure 1 (Continued)

ENVIRONMENTAL		
Test Description	Requirement	Procedure
Resistance to Wave soldering heat. [See Note 2]	See NOTE	TE spec. 109-202, Condition B Solder Temp.: 265 ±5°C, 10 +2/-0 s.
Resistance to Reflow Soldering Heat [See Note 2]	See NOTE	Moisture Soak precondition : 85°C, 85%RH for 168 hours. Pre Heat : 150~200°C, 60~180sec. Peak Temp. : 260+0/-5°C, 20~40sec. Ramp to peak : 3°C max. per second Ramp to cool down : 6°C max. per second Time over liquids (217°C) : 60~150 sec Duration : 3 cycles TE spec. 109-201, Test condition B, Refer to Figure 5.
Temperature life.	See NOTE	EIA-364-17, Method A, Test condition 4 Subject mated Connector 105°C for 168 hours.
Temperature life (Preconditioning).	See NOTE	EIA-364-17, Method A, Test condition 4 Subject mated Connector 105°C for 92 hours.
Thermal shock.	See NOTE	EIA-364-32, Condition I Subject mated specimens to 10 cycles between -55 and 85°C
Humidity-temperature cycling.	See NOTE	EIA-364-31, Method III, Condition B Subject mated specimens to 10 cycles (10 days) between 25 and 65°C at 90 to 95% R.H.
Contact current rating/ Temperature rise.	1.1 A per pin minimum. The temperature rise above ambient shall not exceed 30°C. The ambient condition is still air at 25°C.	EIA-364-70, Method 2 The sample size is a minimum of three mated connectors. The sample shall be soldered on a PC board with the appropriate footprint. Wire the eight power pins (B1, B2, B3, A2, A3, B8, A9, and A10) and the eight nearest ground pins (A4, B4, B7, A12, B13, A15, B16, and B18) in a series circuit. The mated add-in card is included in this circuit. The add-in card shall have 1 oz. copper traces and its mating geometry shall conform to the applicable PCI Express drawings. A thermocouple of 30 AWG or less shall be placed on the card edge finger pad (pins B2 and A9) as close to the mating contact as possible. Conduct a temperature rise vs. current test.

Figure 1 (Continued)

NOTE 1 Shall meet visual requirements, show no physical damage, and meet requirements of additional tests as specified in the Product Qualification and Requalification Test Sequence shown in Figure

2.

NOTE 2 Resistance to soldering process is indicated on notes of customer drawing. Select the appropriate test type which drawing notes are matched with.

Figure 1 (Continued)

3.6. Product Qualification and Requalification Test Sequence

Test or Examination	Test Group								
	A	B	C	D	E	F	G	H	I
	Test Sequence (a)								
Examination of product.	1, 9	1, 8	1, 10	1, 8	1, 8	1, 3	1, 3	1, 3	1, 3
Low level contact resistance.	3, 7	2, 5, 7	2, 5, 7, 9	2, 5, 7					
Dielectric withstanding voltage.					2, 6				
Insulation resistance.					3, 7				
Mating force.	2, 6								
Unmating force.	4, 8								
Durability.	5	3	3	3					
Reseating.		6	8						
Vibration, random.				6					
Solderability.						2			
Resistance to wave soldering heat.							2		
Resistance to Reflow soldering heat									2
Temperature life.		4							
Temperature life (Preconditioning).				4					
Thermal shock.			4		4				
Humidity-temperature cycling.			6		5				
Contact current rating/ Temperature rise.								2	

NOTE (a) Numbers indicate sequence in which test are performed.

Figure 2

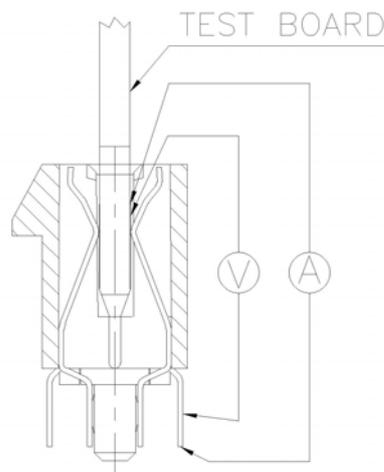
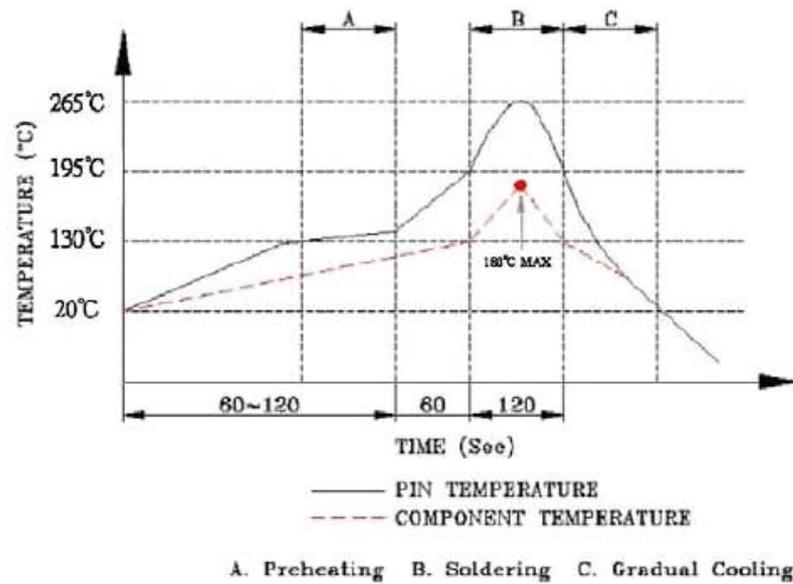


Figure 3 Low Level Contact Resistance



RECOMMENDED WAVE SOLDER

- (1) Tip Temperature : $265 \pm 5^{\circ}\text{C}$
- (2) Tip Temperature Time : 10 sec Max

Figure 4 Temperature Profile of Wave Soldering

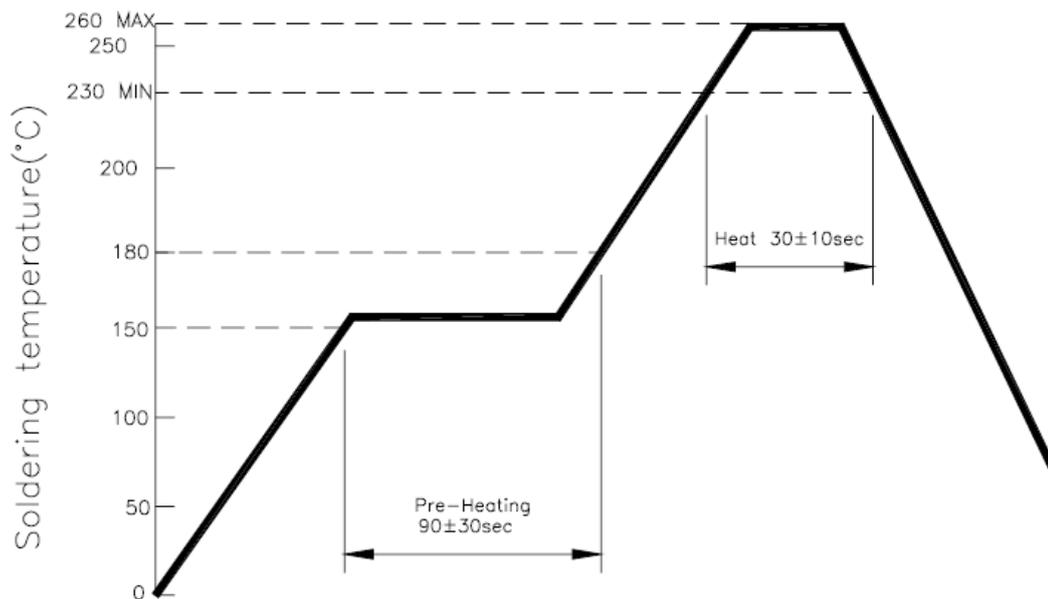


Figure 5 Temperature Profile of Reflow Soldering